



IEEE 3DIC 2019



International 3D Systems Integration Conference
October 8th – 10th, 2019, Sendai, Japan

Call for Papers

The IEEE International 3D Systems Integration Conference (3DIC) will be held at the Hotel Metropolitan Sendai and Miyagino Ward Cultural Center in Sendai, Japan in October 8th-10th, 2019. The deadline for abstract submission is **June 24, 2019**. Abstracts are to be 1 page text (500 words) and 1 page figures.

3DIC 2019 will cover all **3D integration** topics, including 3D/2.5D process technology, materials, equipment, circuits technology, design methodology and applications. The conference invites authors and attendees to submit and interact with researchers from all around the world. Papers are solicited in subject topics, including, but not limited to, the following:

3D/2.5D Integration Technology: Through Si Vias (TSV), Wafer thinning, Wafer alignment, Wafer bonding, Wafer dicing, Interposer (Si/Glass), Optical interconnection, FOWLP, Monolithic 3D integration, Heterogeneous 3D/2.5D integration

3D/2.5D IC Circuits Technology: SOC, Memory, Processor, DSP, FPGA, RF and μ -wave/mm-wave, Analog circuits, Biomedical circuits

3D/2.5D Applications: Artificial Intelligence, Machine Learning, Deep Learning, Imaging, IoT, Memory, Processors, Communications, Networking, Wireless, Biomedical

3D/2.5D Design and Test Methodology: CAD, Synthesis, Design flows, Signal and power integrity analysis and design in 3D/2.5D, Thermal design and analysis, Test and design for test, Mechanical stress and reliability design and analysis

2019 Conference Co-Chairs:

T. Tanaka (Tohoku Univ), P. Franzon (NCSU)

Organizing Committee

Asia: T. Tanaka (Tohoku Univ), K. Lee (SK-hynix), K. N. Chen (NCTU), M. Koyanagi (Tohoku Univ)

USA: P. Franzon (NCSU), B. Patti (Tezzaron), M. Bakir (GA Tech), T. Karnik (Intel)

Europe: P. Ramm (Fraunhofer EMFT), E. Beyne (IMEC), P. Vivet (CEA-Leti), B. Vigna (STMicro)

Conference web site: www.3dic-conf.org

From 2020, 3DIC will be held in USA every year.